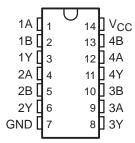
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- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- Inputs Are TTL-Voltage Compatible

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

#### D OR PW PACKAGE (TOP VIEW)



#### description/ordering information

The 'AHCT00 device performs the Boolean function  $Y = \overline{A \bullet B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### ORDERING INFORMATION

TA	T <sub>A</sub> PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC - D	Tape and reel	SN74AHCT00MDREP	AHCT00MEP
-55 C to 125 C	TSSOP – PW	Tape and reel	SN74AHCT00MPWREP	AHT00EP

<sup>&</sup>lt;sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	L
L	X	Н
Х	L	Н

#### logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_{ C } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
٧ <sub>I</sub>	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
loh	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEGT COMPLETIONS		T,	<sub>Δ</sub> = 25°C	;	SN74AHC	UNIT	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNII
\/-··	$I_{OH} = -50 \mu A$	45.77	4.4	4.5		4.4		V
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V
.,	I <sub>OL</sub> = 50 μA	4.5.1			0.1		0.1	
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.44	V
lį	$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Δl <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		2	10			рF

 $<sup>\</sup>ddagger$  This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	ТО	LOAD	T,	λ = 25°C	;	SN74AHC	T00-EP	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A = :: D		0 45 -5		5	6.9	1	8	
t <sub>PHL</sub>	A or B	Y	C <sub>L</sub> = 15 pF		5	6.9	1	8	ns
<sup>t</sup> PLH	A or B	V	C 50 pF		5.5	7.9	1	9	20
t <sub>PHL</sub>	AUID	T T	$C_L = 50 pF$		5.5	7.9	1	9	ns

# noise characteristics, $V_{CC}$ = 5 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 4)

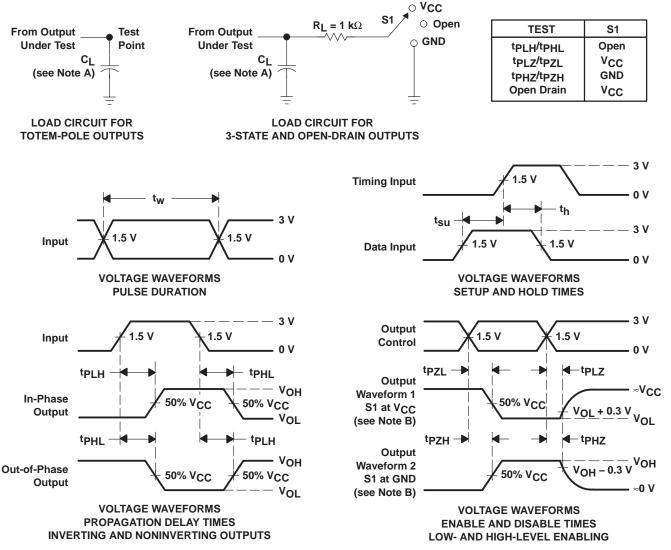
	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.4	0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.4	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		4.5		V
V <sub>IH</sub> (D)	High-level dynamic input voltage	2			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	10.5	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74AHCT00MDREP	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT00MEP
SN74AHCT00MDREP.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT00MEP
SN74AHCT00MPWREP	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT00EP
SN74AHCT00MPWREP.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT00EP
V62/03653-01XE	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT00EP
V62/03653-01YE	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT00MEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF SN74AHCT00-EP:

● Catalog : SN74AHCT00

• Military : SN54AHCT00

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

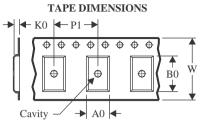
• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

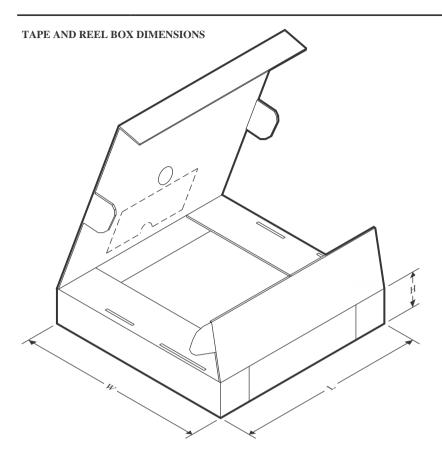
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT00MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT00MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT00MDREP	SOIC	D	14	2500	353.0	353.0	32.0
SN74AHCT00MPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0

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